- **Function and Pinout Compatible With FCT** and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- **Edge-Rate Control Circuitry for** Significantly Improved Noise **Characteristics**
- Ioff Supports Partial-Power-Down Mode • Operation
- **ESD Protection Exceeds JESD 22** - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- **Matched Rise and Fall Times**
- Fully Compatible With TTL Input and **Output Logic Levels**
- **3-State Outputs**
- **CY54FCT373T**
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT373T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current

description

The 'FCT373T devices consist of eight latches with 3-state outputs for bus-organized applications. When the latch-enable (LE) input is high, the flip-flops appear transparent to the data. Data that meets the required setup times are latched when LE transitions from high to low. Data appears on the bus when the output-enable ($\overline{\mathsf{OE}}$) input is low. When OE is high, the bus output is in the high-impedance state. In this mode, data can be entered into the latches.

These devices are fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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CY54FCT373T D PACKAGE
CY74FCT373T Q OR SO PACKAGE
(TOP VIEW)

OE		O_{20}]∨ _{cc}
0 ₀	2	19	07
D_0		18] D ₇
D ₁	4	17] D ₆
0 ₁	[5	16] O ₆
0 ₂	6	15] O ₅
D_2	[7	14] D ₅
D_3		13] D ₄
O3	[9	12	04
GND		11	LE

CY54FCT373T, CY74FCT373T 8-BIT LATCHES WITH 3-STATE OUTPUTS SCCS021B - MAY 1994 - REVISED OCTOBER 2001

TA	PACI	(AGE [†]	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING					
	QSOP – Q	Tape and reel	4.7	CY74FCT373CTQCT	FCT373C					
	SOIC – SO	Tube	4.7	CY74FCT373CTSOC	FCT373C					
	5010 - 50	Tape and reel	4.7	CY74FCT373CTSOCT	FU1373U					
–40°C to 85°C	QSOP – Q	Tape and reel	5.2	CY74FCT373ATQCT	FCT373A					
-40 C 10 85 C	SOIC – SO	Tube	5.2	CY74FCT373ATSOC	FCT373					
	3010 - 30	Tape and reel	5.2	CY74FCT373ATSOCT	1013/3					
	SOIC – SO	Tube	8	CY74FCT373TSOC	FCT373					
	3010 - 30	Tape and reel	8	CY74FCT373TSOCT	F01373					
–55°C to 125°C	CDIP – D	Tube	5.6	CY54FCT373ATDMB						

ORDERING INFORMATION

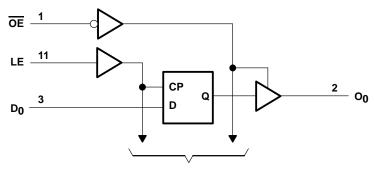
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPUTS		OUTPUT
OE	LE	D	0
L	Н	Н	н
L	н	L	L
L	L	Х	Q ₀
н	Х	Х	Z

H = High logic level, L = Low logic level, X = Don't care, Z = High-impedance state, Q_n = Previous state of flip flops (Q_{n-1})

logic diagram (positive logic)



To Seven Other Channels



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absolute maximum rating over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range to ground potential	0.5 V to 7 V
DC input voltage range	\ldots -0.5 V to 7 V
DC output voltage range	\ldots -0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ_{JA} (see Note 1): Q package	68°C/W
SO package	58°C/W
Ambient temperature range with power applied, T _A	65°C to 135°C
Storage temperature range, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

		CY54FCT373T			CY	'3T	UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-12			-32	mA
IOL	Low-level output current			32			64	mA
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

BAR AMETER	TEST CONDITIONS		CY	54FCT37	73T	CY	74FCT37	′3T		
PARAMETER	IESI CC	DITIONS	MIN	TYP [†]	MAX	MIN	түр†	MAX	UNIT	
Maria	$V_{CC} = 4.5 \text{ V}, \qquad I_{IN} = -18 \text{ r}$	nA		-0.7	-1.2				v	
VIK	$V_{CC} = 4.75 \text{ V}, \qquad I_{IN} = -18 \text{ r}$	nA					-0.7	YPT MAX -0.7 -1.2 3.3	v	
	$V_{CC} = 4.5 V$, $I_{OH} = -12$	mA	2.4	3.3						
VOH	$V_{CC} = 4.75 V$ $I_{OH} = -32$	mA				2			V	
	$I_{OH} = -15$	mA				2.4	3.3			
Ve	$V_{CC} = 4.5 V$, $I_{OL} = 32 m$	۱A		0.3	0.55				v	
VOL	$V_{CC} = 4.75 \text{ V}, I_{OL} = 64 \text{ m}$	۱A					0.3	0.55	v	
V _{hys}	All inputs			0.2			0.2		V	
	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = V_{CC}$	<u>,</u>			5				μA	
η η	$V_{CC} = 5.25 \text{ V}, V_{IN} = V_{CC}$, ,						5		
hu i	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$	V			±1				υA	
ΠΗ	$V_{CC} = 5.25 \text{ V}, V_{IN} = 2.7 \text{ V}$	V						±1	μΛ	
	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$	V			±1					
ΊL	$V_{CC} = 5.25 \text{ V}, V_{IN} = 0.5 \text{ V}$	V						±1	μΛ	
	V _{CC} = 5.5 V, V _{OUT} = 2.	7 V			10					
102H	V _{CC} = 5.25 V, V _{OUT} = 2.	7 V						10	μΛ	
1071	V _{CC} = 5.5 V, V _{OUT} = 0.	5 V			-10				ıιΔ	
'OZL	V _{CC} = 5.25 V, V _{OUT} = 0.	5 V						-10	μΛ	
loot	$V_{CC} = 5.5 V, V_{OUT} = 0$	V	-60	-120	-225				mΔ	
105+	V _{CC} = 5.25 V, V _{OUT} = 0	V				-60	-120	-225	Αμ Αμ Αμ Αμ Αμ	
l _{off}	V _{CC} = 0 V, V _{OUT} = 4.	5 V			±1			±1	μA	
	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}$	$V_{\rm IN} \ge V_{\rm CC} - 0.2$	/	0.1	0.2				m۵	
		$V_{\rm IN} \ge V_{\rm CC} - 0.2$	/				0.1	0.2		
Alco	V_{CC} = 5.5 V, V_{IN} = 3.4 V§, f		Outputs open 0.5 2					m۵		
IIL IOZH IOZL IOS [‡]	$V_{CC} = 5.25 \text{ V}, \text{ V}_{IN} = 3.4 \text{ V}\$,$	f ₁ = 0, Outputs open					0.5	2	IIIA	

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

* Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

§ Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

PARAMETER		TEST CONDITION	6	CY	54FCT3	73T	CY	74FCT37	′3T	
PARAMETER	TEST CONDITIONS				$\begin{array}{c c c c c c c c c c c c c c c c c c c $	UNIT				
ICCD			OE = GND,		0.06	0.12				mA/
"CCD"	One input switch	$V_{CC} = 5.25 \text{ V}, \text{ Outputs open,}$ One input switching at 50% duty cycle, $\overline{\text{OE}} = \text{GND},$ $V_{IN} \le 0.2 \text{ V or } V_{IN} \ge V_{CC} - 0.2 \text{ V}$						0.06	0.12	MHz
	V _{CC} = 5.5 V,	One bit switching at f ₁ = 10 MHz			0.7	1.4				
	$\frac{Outputs open,}{OE} = GND,$ LE = V _{CC}	Outputs open, at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1	2.4				
		Eight bits switching at $f_1 = 2.5$ MHz			1.3	2.6				
1#		at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		3.3	10.6				~ ^
IC.,	Voo - 5 25 V	One bit switching at $f_1 = 10 \text{ MHz}$						0.7	1.4	ma
$IC^{\#} \qquad \begin{array}{ c c c c c } \hline \overline{OE} = GND, \\ LE = VCC & at 50\% \ duty \ cycle & VIN \leq 0.2 \ Vole \\ at f_1 = 2.5 \ MHz \\ at 50\% \ duty \ cycle & VIN \geq VCC - \\ \hline VIN = 3.4 \ Vole \\ VIN \geq VCC - \\ \hline VIN \geq 0.2 \ Vole \ Vole \\ \hline VIN \geq 0.2 \ Vole \\ \hline VIN \geq 0.2 \ Vole \\ \hline VIN \geq 0.2 \ Vole \ Vole \ Vole \ Vole \\ $	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					1	2.4		
	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array} \end{array} \label{eq:VIN}$					1.3	2.6			
		at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					3.3	10.6	
Ci					6	10		6	10	pF
Co					8	12		8	12	pF

Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

This parameter is derived for use in total power-supply calculations.

[#] IC = ICC + Δ ICC × D_H × N_T + ICCD (f₀/2 + f₁ × N₁)

- Where:
- $I_C = \mbox{Total supply current} \\ I_{CC} = \mbox{Power-supply current with CMOS input levels}$
- ΔI_{CC} = Power-supply current for a TTL high input (V_{IN} = 3.4 V)

 D_H = Duty cycle for TTL inputs high NT = Number of TTL inputs at D_H

- I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

= Clock frequency for registered devices, otherwise zero f₀

- f1 = Input signal frequency
- = Number of inputs changing at f1 N_1

All currents are in milliamperes and all frequencies are in megahertz.

Il Values for these conditions are examples of the I_{CC} formula.



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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		CY54FC	T373T	CY54FCT	UNIT	
		MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, LE high	6		6		ns
t _{su}	Setup time, data before LE1	2		2		ns
th	Hold time, data after LE↑	1.5		1.5		ns

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		CY74FCT373T		CY74FCT	373AT	CY74FCT	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, LE high	6		5		5		ns
t _{su}	Setup time, data before LE↑	2		2		2		ns
th	Hold time, data after LE↑	1.5		1.5		1.5		ns

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY54FCT	UNIT	
FARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	
^t PLH	D	0	1.5	5.6	ns
^t PHL	U	0	1.5	5.6	115
^t PLH	LE	0	2	9.8	ns
^t PHL		0	2	9.8	115
^t PZH	OE	0	1.5	7.5	200
^t PZL	ŬE.	0	1.5	7.5	ns
^t PHZ	OE	0	1.5	6.5	200
^t PLZ	ŬE.	0	1.5	6.5	ns

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY74FC	T373T	CY74FCT	373AT	CY74FCT	Г373CT	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	
^t PLH	D	О	1.5	8	1.5	5.2	1.5	4.7	
^t PHL		0	1.5	8	1.5	5.2	1.5	4.7	ns
^t PLH	LE	0	2	13	2	8.5	2	5.5	
^t PHL		0	2	13	2	8.5	2	5.5	ns
^t PZH	OE	0	1.5	12	1.5	6.5	1.5	5.5	ns
^t PZL	ÜE	0	1.5	12	1.5	6.5	1.5	5.5	115
^t PHZ	OE	0	1.5	7.5	1.5	5.5	1.5	5	ns
^t PLZ	UE	0	1.5	7.5	1.5	5.5	1.5	5	115



07V **S1** O Open **500** Ω From Output From Output Test $\Lambda \Lambda \Lambda$ TEST O GND **S1** Under Test **Under Test** Point tPLH/tPHL Open C_L = 50 pF $C_1 = 50 \text{ pF}$ 2 **500** Ω **500** Ω 7 V (see Note A) tPLZ/tPZL (see Note A) tPHZ/tPZH Open LOAD CIRCUIT FOR LOAD CIRCUIT FOR **TOTEM-POLE OUTPUTS 3-STATE OUTPUTS** 3 V **Timing Input** 1.5 V 0 V tw th 3 V tsu 3 V 1.5 V 1.5 V Input 1.5 V 1.5 V **Data Input** 0 V 0 V **VOLTAGE WAVEFORMS VOLTAGE WAVEFORMS** PULSE DURATION SETUP AND HOLD TIMES 3 V 3 V Output 1.5 V 1.5 V 1.5 V 1.5 V Input Control 0 V 0 V -t_{PLZ} ^tPLH ^tPHL tPZL -┢ ۷он Output ≈3.5 V In-Phase 1.5 V 1.5 V Waveform 1 .5 V Output /_{OL} + 0.3 V (see Note B) VOL VOL ^tPHL Κ ^tPLH ^tPZH ^tPHZ ۷он Output ۷он **Out-of-Phase** VOH – 0.3 V 1.5 V 1.5 V Waveform 2 5 V Output (see Note B) ≈0 V VOL **VOLTAGE WAVEFORMS VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES** ENABLE AND DISABLE TIMES INVERTING AND NONINVERTING OUTPUTS LOW- AND HIGH-LEVEL ENABLING

PARAMETER MEASUREMENT INFORMATION

NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9221701MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9221701MR A	Samples
5962-9221702MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9221702MR A CY54FCT373ATDM B	Samples
5962-9221703M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9221703M2A	Samples
CY54FCT373ATDMB	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9221702MR A CY54FCT373ATDM B	Samples
CY74FCT373ATQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT373A	Samples
CY74FCT373ATQCTE4	ACTIVE	SSOP	DBQ	20	2500	TBD	Call TI	Call TI	-40 to 85		Samples
CY74FCT373ATSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT373A	Samples
CY74FCT373TSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT373	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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PACKAGE OPTION ADDENDUM

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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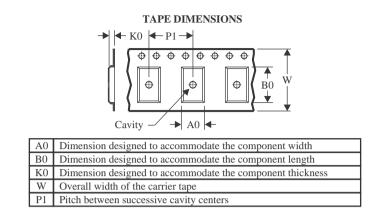


TEXAS

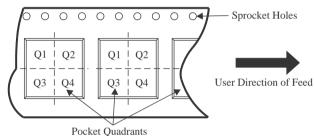
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	-	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT373ATQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

3-Jun-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT373ATQCT	SSOP	DBQ	20	2500	356.0	356.0	35.0

TEXAS INSTRUMENTS

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TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-9221703M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
CY74FCT373ATSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT373TSOC	DW	SOIC	20	25	507	12.83	5080	6.6

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